

**TURBO 2 ULTRAFast HIGH VOLTAGE RECTIFIER**
**Table 1: Main Product Characteristics**

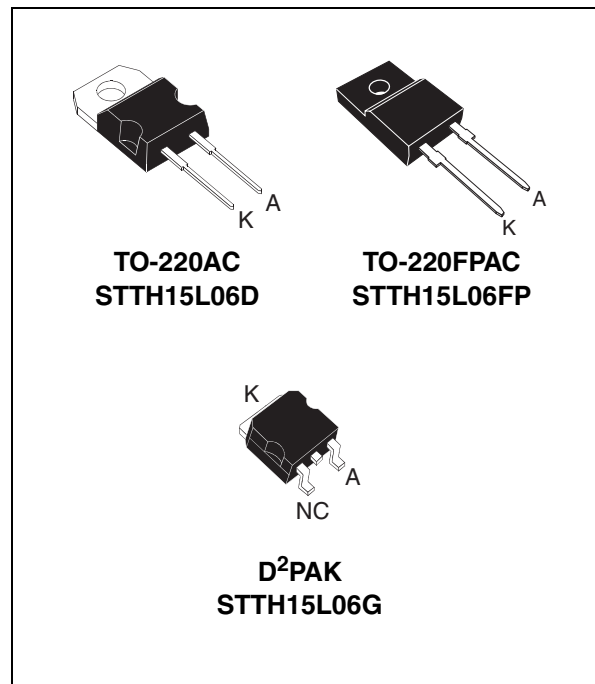
$I_{F(AV)}$	<b>Up to 20 A</b>
$V_{RRM}$	<b>600 V</b>
$T_j$	<b>175°C</b>
$V_F$ (typ)	<b>0.95 V</b>
$t_{rr}$ (max)	<b>55 ns</b>

**FEATURES AND BENEFITS**

- Ultrafast switching
- Low reverse current
- Low thermal resistance
- Reduces switching & conduction losses

**DESCRIPTION**

The STTH15L06, which is using ST Turbo 2 600V technology, is specially suited for use in switching power supplies, and industrial applications, as rectification and discontinuous mode PFC boost diode.


**Table 2: Order Codes**

Part Number	Marking
STTH15L06D	STTH15L06D
STTH15L06G	STTH15L06G
STTH15L06G-TR	STTH15L06G
STTH15L06FP	STTH15L06FP

**Table 3: Absolute Ratings (limiting values)**

Symbol	Parameter		Value	Unit	
$V_{RRM}$	Repetitive peak reverse voltage		600	V	
$I_{F(RMS)}$	RMS forward voltage		30	A	
$I_{F(AV)}$	Average forward current	TO-220AC / D²PAK	$T_c = 140^\circ\text{C} \quad \delta = 0.5$ $T_c = 120^\circ\text{C} \quad \delta = 0.5$	15 20	A
		TO-220FPAC	$T_c = 90^\circ\text{C} \quad \delta = 0.5$	15	
	Surge non repetitive forward current		$t_p = 10\text{ms}$ sinusoidal	130	
$T_{stg}$	Storage temperature range		-65 to + 175	°C	
$T_j$	Maximum operating junction temperature		175	°C	

**Table 4: Thermal Resistance**

Symbol	Parameter		Value (max.)	Unit
$R_{th(j-c)}$	Junction to case	TO-220AC / D <sup>2</sup> PAK	1.7	°C/W
		TO-220FPAC	4	

**Table 5: Static Electrical Characteristics (per diode)**

Symbol	Parameter	Test conditions		Min.	Typ	Max.	Unit
$I_R^*$	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			15	$\mu\text{A}$
		$T_j = 150^\circ\text{C}$			40	400	
$V_F^{**}$	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 15\text{A}$			1.55	V
		$T_j = 150^\circ\text{C}$			0.95	1.2	

Pulse test: \*  $t_p = 5 \text{ ms}$ ,  $\delta < 2\%$

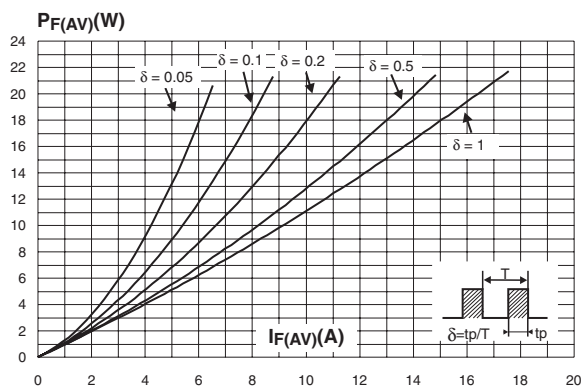
\*\*  $t_p = 380 \mu\text{s}$ ,  $\delta < 2\%$

To evaluate the conduction losses use the following equation:  $P = 0.94 \times I_{F(AV)} + 0.017 I_F^2(\text{RMS})$

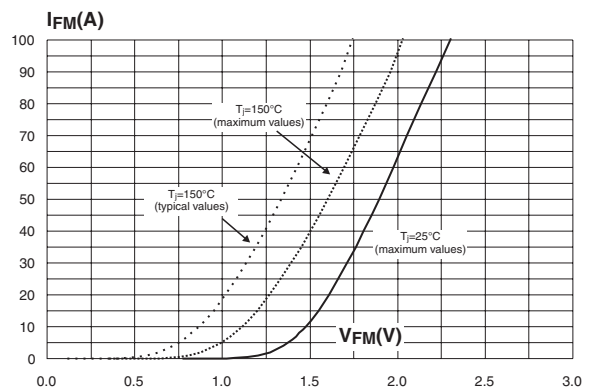
**Table 6: Dynamic Characteristics**

Symbol	Parameter	Test conditions			Min.	Typ	Max.	Unit
$t_{rr}$	Reverse recovery time	$T_j = 25^\circ\text{C}$	$I_F = 0.5\text{A}$ $I_{rr} = 0.25\text{A}$ $I_R = 1\text{A}$			55	ns	
			$I_F = 1\text{A}$ $di_F/dt = 50 \text{ A}/\mu\text{s}$ $V_R = 30\text{V}$		60	85		
$I_{RM}$	Reverse recovery current	$T_j = 125^\circ\text{C}$	$I_F = 15\text{A}$ $V_R = 400\text{V}$ $di_F/dt = 100 \text{ A}/\mu\text{s}$		8.5	12	A	
$t_{fr}$	Forward recovery time	$T_j = 25^\circ\text{C}$	$I_F = 15\text{A}$ $di_F/dt = 100 \text{ A}/\mu\text{s}$ $V_{FR} = 1.1 \times V_{Fmax}$			300	ns	
$V_{FP}$	Forward recovery voltage	$T_j = 25^\circ\text{C}$	$I_F = 15\text{A}$ $di_F/dt = 100 \text{ A}/\mu\text{s}$ $V_{FR} = 1.1 \times V_{Fmax}$		3		V	

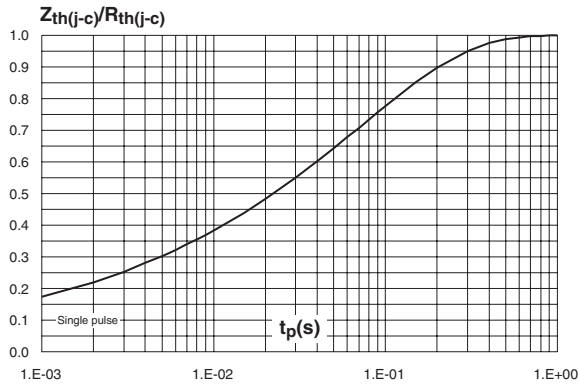
**Figure 1: Conduction losses versus average forward current**



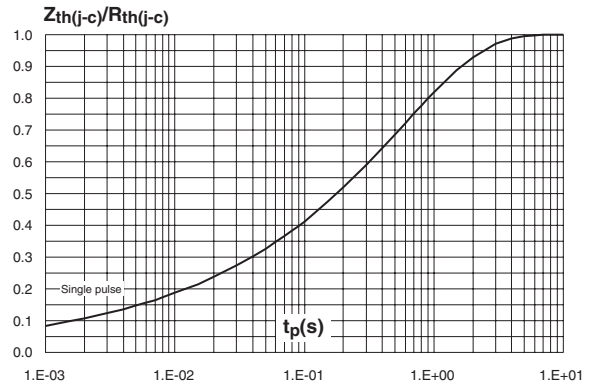
**Figure 2: Forward voltage drop versus forward current**



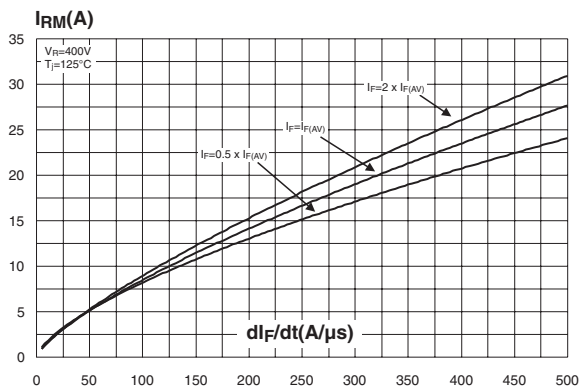
**Figure 3: Relative variation of thermal impedance junction to case versus pulse duration (TO-220AC & D<sup>2</sup>PAK)**



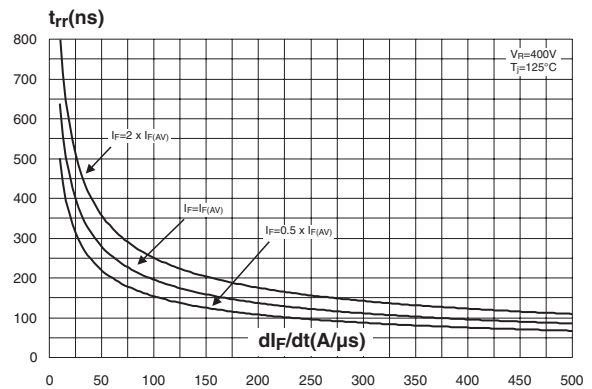
**Figure 4: Relative variation of thermal impedance junction to case versus pulse duration (TO-220FPAC)**



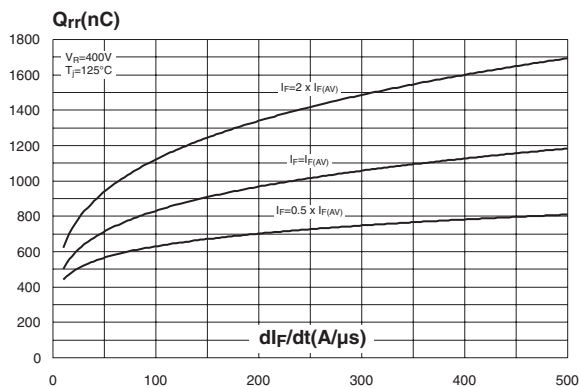
**Figure 5: Peak reverse recovery current versus  $di_F/dt$  (typical values)**



**Figure 6: Reverse recovery time versus  $di_F/dt$  (typical values)**



**Figure 7: Reverse recovery charges versus  $di_F/dt$  (typical values)**



**Figure 8: Reverse recovery softness factor versus  $di_F/dt$  (typical values)**

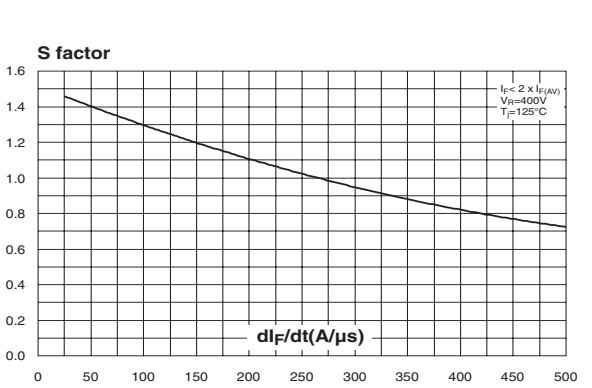


Figure 9: Relative variations of dynamic parameters versus junction temperature

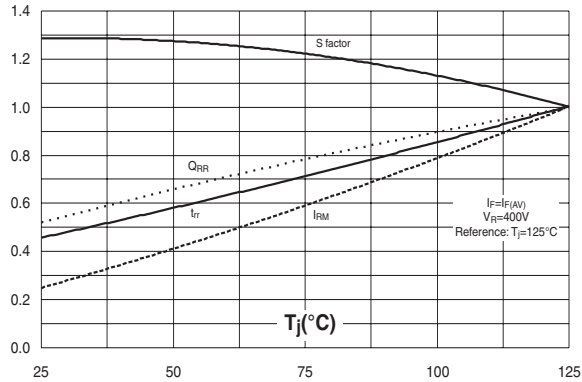


Figure 10: Transient peak forward voltage versus  $di_F/dt$  (typical values)

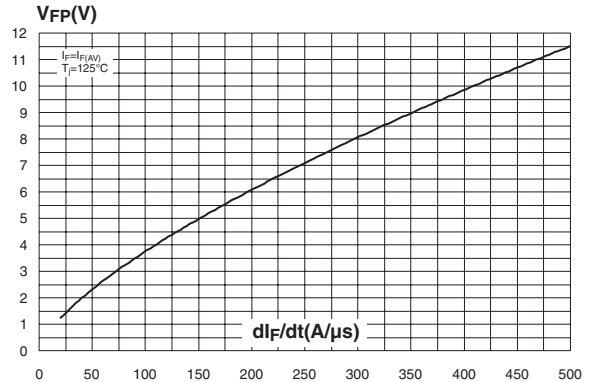


Figure 11: Forward recovery time versus  $di_F/dt$  (typical values)

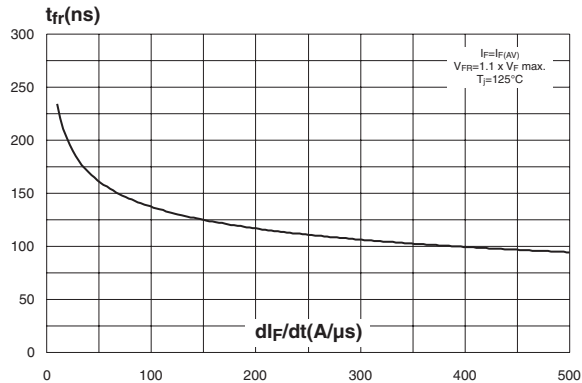


Figure 12: Junction capacitance versus reverse voltage applied (typical values)

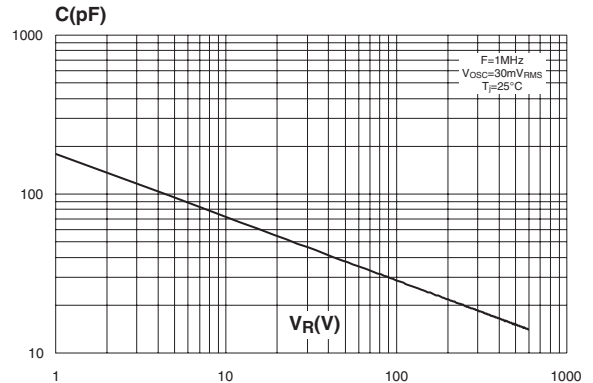


Figure 13: Thermal resistance junction to ambient versus copper surface under tab (epoxy FR4,  $e_{CU} = 35\mu m$ ) (D<sup>2</sup>PAK)

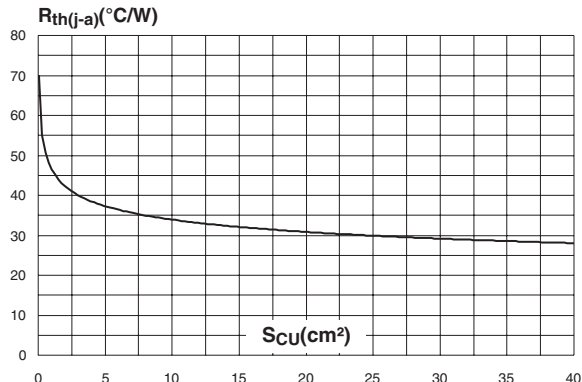


Figure 14: D<sup>2</sup>PAK Package Mechanical Data

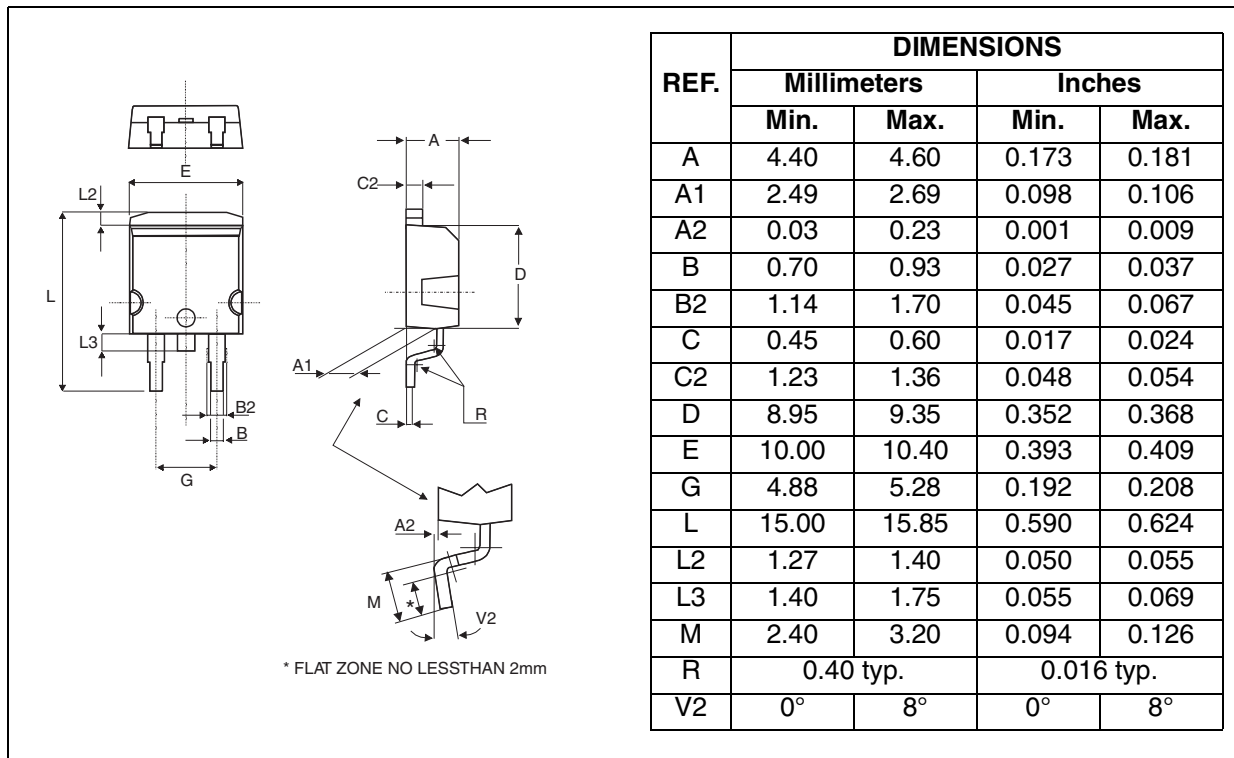


Figure 15: D<sup>2</sup>PAK Foot Print Dimensions (in millimeters)

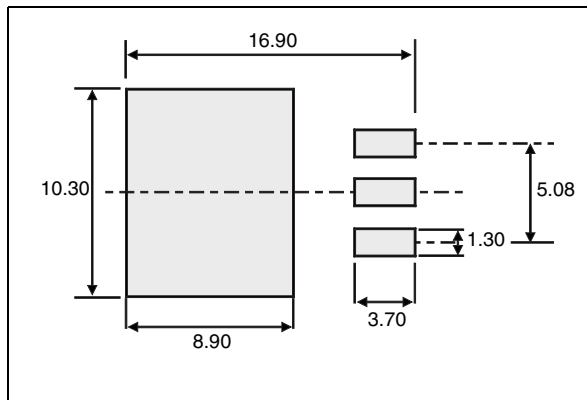


Figure 16: TO-220FPAC Package Mechanical Data

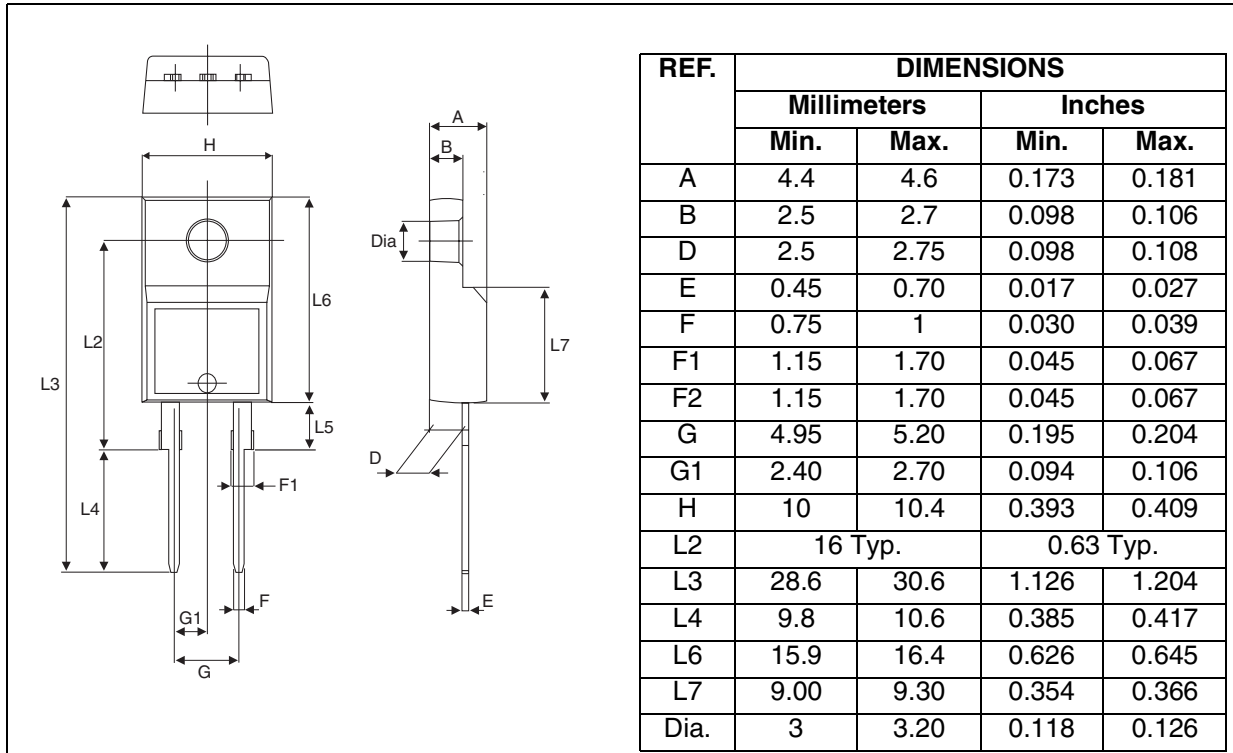


Figure 17: TO-220AC Package Mechanical Data

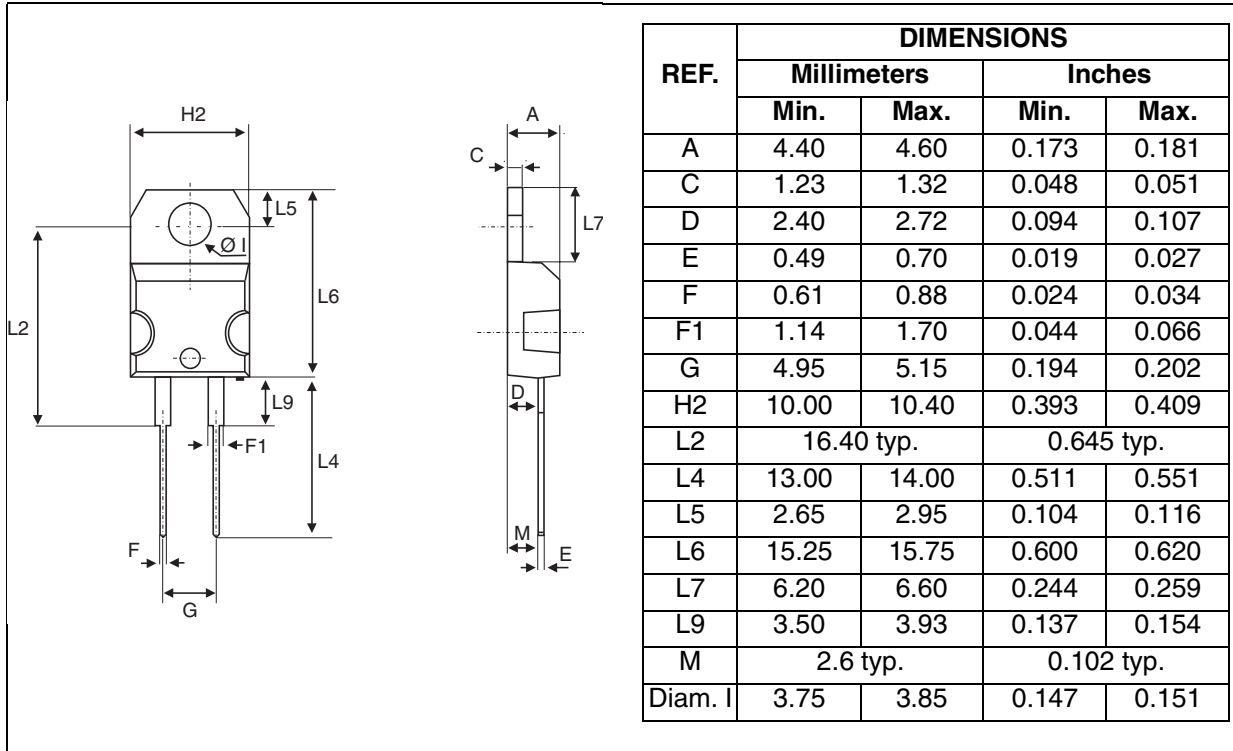


Table 7: Ordering Information

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STTH15L06D	STTH15L06D	TO-220AC	1.90 g	50	Tube
STTH15L06G	STTH15L06G	D <sup>2</sup> PAK	1.48 g	50	Tube
STTH15L06G-TR	STTH15L06G	D <sup>2</sup> PAK	1.48 g	1000	Tape & eel
STTH15L06FP	STTH15L06FP	TO-220FPAC	1.70 g	50	Tube

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.8 m.N. (TO-220FPAC) / 0.55 m.N. (TO-220AC)
- Maximum torque value: 1.0 m.N. (TO-220FPAC) / 0.70 m.N. (TO-220AC)

Table 8: Revision History

Date	Revision	Description of Changes
07-Sep-2004	1	First issue

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